



ALLIANCE MEMORY MDS REPORT

Part Number:			ASFC8G31MB-51BIN						
Part Weight(mg):			341.6119974						
No.	Name of COMPONENT	Material Name	Component Weight(mg)	Materials Analysis (Element)	CAS Number	Material Mass (mg)	Material Analysis (Weight %)	Package Composition (Weight %)	Package Composition (Weight ppm)
1	Ag wire	GX2K	0.0470	Silver	7440-22-4	0.0465300	99.00%	0.0136%	136.2
				Others	Trade secret	0.0004700	1.00%	0.0001%	1.4
2	Film	EM-760L2-P	8.4530	Acrylic Resin	Trade secret	4.1419700	49.00%	1.2125%	12124.8
				Silica, amorphous	7631-86-9	3.8038500	45.00%	1.1135%	11135.0
				Phenol Resin	Trade secret	0.5071800	6.00%	0.1485%	1484.7
3	Film	EM-310WJ1-P	0.3850	Epoxy Resin	Trade secret	0.0962500	25.00%	0.0282%	281.8
				Phenol Resin	Trade secret	0.0962500	25.00%	0.0282%	281.8
				Silica, amorphous	7631-86-9	0.1540000	40.00%	0.0451%	450.8
				Synthetic rubber	Trade secret	0.0385000	10.00%	0.0113%	112.7
4	Substrate_HL832NS+AUS308	Cu plating	131.5230	Copper	7440-50-8	62.6665363	47.65%	18.3444%	183443.6
		Au plating		Gold	7440-57-5	0.0350193	0.03%	0.0103%	102.5
		Ni plating		Nickel	7440-02-0	0.2539959	0.19%	0.0744%	743.5
		copper foil		Copper	7440-50-8	24.8740677	18.91%	7.2814%	72813.8
		HL830NS		Thermosetting resin (including inorganic filler)	Trade secret	19.1954991	14.59%	5.6191%	56190.9
				Continuous Filament Fiber Glass	Trade secret	10.3360375	7.86%	3.0257%	30256.7
		AUS308		Cured Resin	Trade secret	8.7236957	6.63%	2.5537%	25536.9
				Phthalocyanine blue	147-14-8	0.0212423	0.02%	0.0062%	62.2
				Organic pigment	Trade secret	0.0212423	0.02%	0.0062%	62.2
				Silica	7631-86-9	1.3028892	0.99%	0.3814%	3813.9
				Barium sulfate	7727-43-7	1.3028892	0.99%	0.3814%	3813.9
				Talc	14807-96-6	1.3028892	0.99%	0.3814%	3813.9
				Organic filler	Trade secret	1.3028892	0.99%	0.3814%	3813.9
				Antifoamer and Leveling agent	Trade secret	0.1841046	0.14%	0.0539%	538.9
		5		SOLDER BALL	M770GE	23.0320	Tin	7440-31-5	22.3824976
Silver	7440-22-4		0.4606400				2.00%	0.1348%	1348.4
Copper	7440-50-8		0.1727400				0.75%	0.0506%	505.7
Nickel	7440-02-0		0.0161224				0.07%	0.0047%	47.2
6	Compound	KE-G2250AH-H	161.9430	Silica(Fused)(1)	60676-86-0	121.7811360	75.20%	35.6490%	356489.6
				Silica(Fused)(2)	7631-86-9	16.1943000	10.00%	4.7406%	47405.5
				Epoxy resin (1)	UNDISCLOSED	5.6680050	3.50%	1.6592%	16591.9
				Epoxy resin (2)	UNDISCLOSED	8.9068650	5.50%	2.6073%	26073.0
				Phenol resin	UNDISCLOSED	8.9068650	5.50%	2.6073%	26073.0
				Carbon Black	1333-86-4	0.4858290	0.30%	0.1422%	1422.2
7	Capacitor	Capacitor*2 27-AE25-9009K 0201 X6S 1UF 6.3V 20% 15K	0.6000	Barium-titanium-trioxide	12047-27-7	0.4648200	77.47%	0.1361%	1360.7
				Nickel	7440-02-0	0.0430200	7.17%	0.0126%	125.9
				Copper	7440-50-8	0.0633600	10.56%	0.0185%	185.5
				Nickel	7440-02-0	0.0121200	2.02%	0.0035%	35.5
				Tin	7440-31-5	0.0166800	2.78%	0.0049%	48.8
8	Resistor	Resistor*1 27-AM23-800XR 0201 300 OHM 1% 1/20w 10k	0.1400	Al2O3	1344-28-1	0.1097600	78.40%	0.0321%	321.3
				Glass Frit	65997-18-4	0.0016100	1.15%	0.0005%	4.7
				Ag	7440-22-4	0.0045500	3.25%	0.0013%	13.3
				Cr	7440-47-3	0.0025550	1.83%	0.0007%	7.5
				Ni	7440-02-0	0.0025550	1.83%	0.0007%	7.5
				Epoxy	38891-59-7	0.0038500	2.75%	0.0011%	11.3
				Pb	65997-18-4	0.0005600	0.40%	0.0002%	1.6
				RuO2	12036-10-1	0.0005600	0.40%	0.0002%	1.6
				Ni	7440-02-0	0.0070000	5.00%	0.0020%	20.5
				Sn	7440-31-5	0.0070000	5.00%	0.0020%	20.5
9	Tin Paste	96SCCR32	0.1230	Tin	7440-31-5	0.0953250	77.50%	0.0279%	279.0
				Silver	7440-22-4	0.0067650	5.50%	0.0020%	19.8
				Rosin	8050-09-7	0.0067650	5.50%	0.0020%	19.8
				Rosin, reaction products with acrylic acid, hydrogenated	144413-22-9	0.0067650	5.50%	0.0020%	19.8
				Resin acids and Rosin acids, hydrogenated, Me esters	8050-15-5	0.0067650	5.50%	0.0020%	19.8
				Copper	7440-50-8	0.0006150	0.50%	0.0002%	1.8
10	Die 2	234.25*470.28*3.5+/-0.3	14.6970	Si	7440-21-3	14.6970000	100.00%	4.3022%	43022.5
11	Die 1	50.24*145.56*2.4+/-0.2	0.6690	Si	7440-21-3	0.6690000	100.00%	0.1958%	1958.4
Total Package Weight			341.6119974	341.6119974			100.0000%	1000000.0	